

### Description

The DMN2020LSN uses advanced trench technology

to provide excellent  $R_{\text{DS}(\text{ON})},$  low gate charge and

operation with gate voltages as low as 2.5V. This

device is suitable for use as a Battery protection

or in other Switching application.

### **General Features**

V<sub>DS</sub> = 20V I<sub>D</sub> =6A

 $R_{DS(ON)} < 17m\Omega @ V_{GS}=4.5V$ 

ESD=2500HBM

### Application

Battery protection

Load switch

Uninterruptible power supply

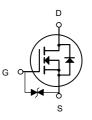
### Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMN2020LSN	SOT-23	HXY MOSFET	3000

### Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
Vds	Drain-Source Voltage	20	V
V <sub>GS</sub>	Gate-Source Voltage	±12	V
Ι <sub>D</sub>	Drain Current-Continuous	6	A
DM	Drain Current-Pulsed (Note 1)	30	A
P <sub>D</sub>	Maximum Power Dissipation	1.4	W
Тј,Тѕтс	Operating Junction and Storage Temperature Range	-55 To 150	°C
Reja	Thermal Resistance, Junction-to-Ambient (Note 2)	89	°C/W





N-Channel MOSFET

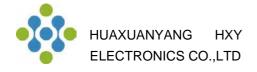


## **Electrical Characteristics (T<sub>A</sub>=25°Cunless otherwise noted)**

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS}$ =0V I <sub>D</sub> =250µA	20		-	V
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =20V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	lgss	$V_{GS}=\pm 10V, V_{DS}=0V$	-	-	±10	μA
Gate Threshold Voltage	VGS(th)	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	0.45	0.7	1.0	V
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =6.5A	-	14	17	mΩ
Drain-Source On-State Resistance	Rds(on)	V <sub>GS</sub> =2.5V, I <sub>D</sub> =5.5A	-	18	23	mΩ
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =5A	-	28	40	mΩ
Forward Transconductance	gfs	V <sub>DS</sub> =5V,I <sub>D</sub> =6.5A	8	-	-	S
Input Capacitance	Clss		-	660	-	PF
Output Capacitance	Coss	V <sub>DS</sub> =10V,V <sub>GS</sub> =0V, F=1.0MHz	-	160	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	87	-	PF
Turn-on Delay Time	td(on)		-	0.5		nS
Turn-on Rise Time	tr	V <sub>DD</sub> =10V,R <sub>L</sub> =1. 5Ω	-	1		nS
Turn-Off Delay Time	td(off)	$V_{GS}$ =5V, $R_{GEN}$ =3 $\Omega$	-	12		nS
Turn-Off Fall Time	t <sub>f</sub>		-	4		nS
Total Gate Charge	Qg		-	8		nC
Gate-Source Charge	Qgs	V <sub>DS</sub> =10V,I <sub>D</sub> =6.5A,	-	2.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =4.5V	-	3	-	nC
Diode Forward Voltage (Note 3)	Vsd	V <sub>GS</sub> =0V,I <sub>S</sub> =6.5A	-	-	1.2	V
Diode Forward Current (Note 2)	ls		-	-	6.5	A

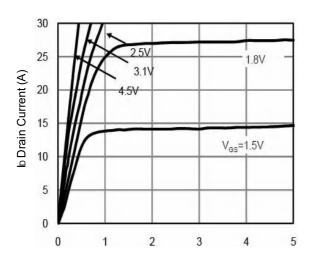
#### Notes:

Repetitive Rating: Pulse width limited by maximum junction temperature. Surface Mounted on FR4 Board, t  $\leq$  10 sec. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2%. Guaranteed by design, not subject to production



# DMN2020LSN N-Channel Enhancement Mode MOSFET

### **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

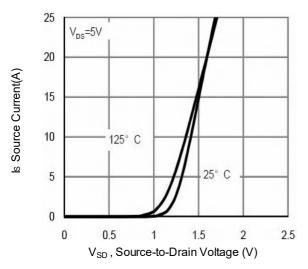


Fig.3 Forward Characteristics of Reverse

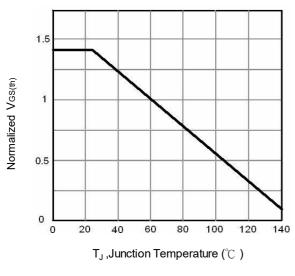


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

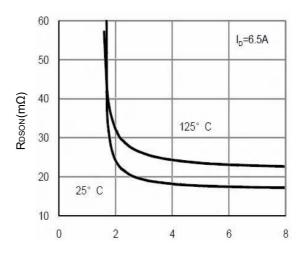
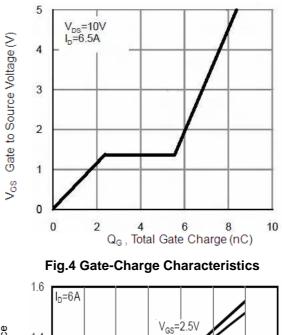


Fig.2 On-Resistance vs. Gate-Source



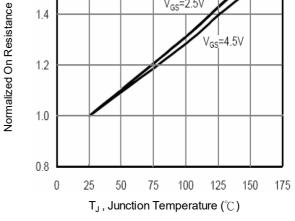
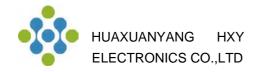
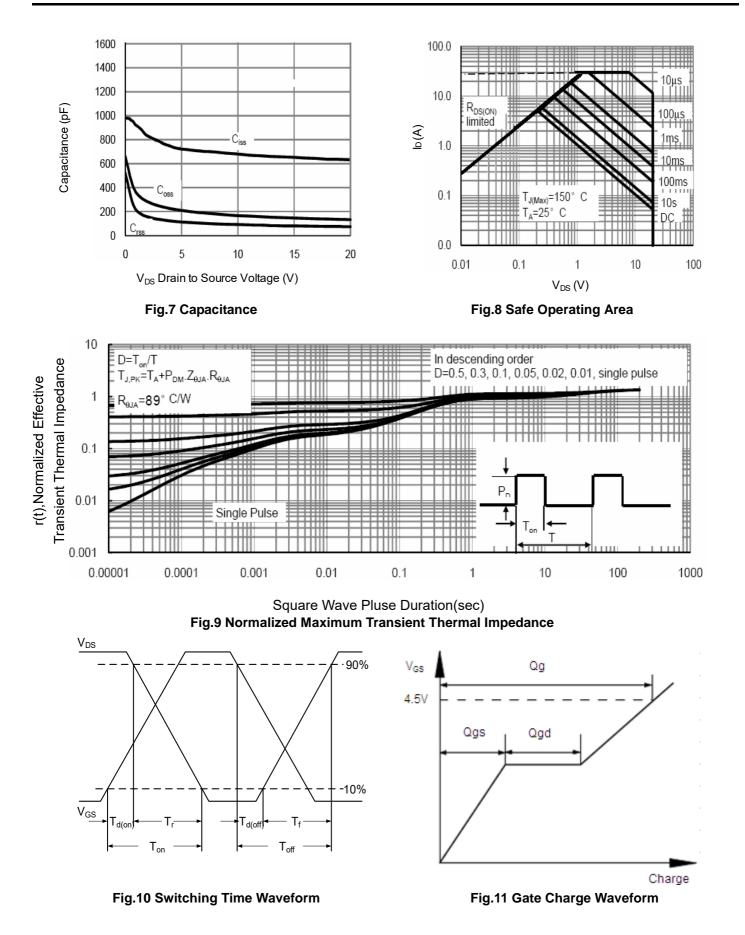


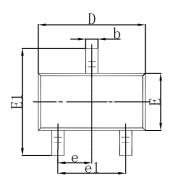
Fig.6 Normalized  $R_{\text{DSON}}$  vs.  $T_{\text{J}}$ 

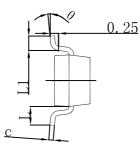


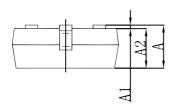




## **SOT-23 Package Outline Dimensions**

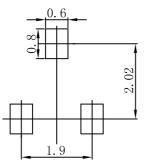






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

# SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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